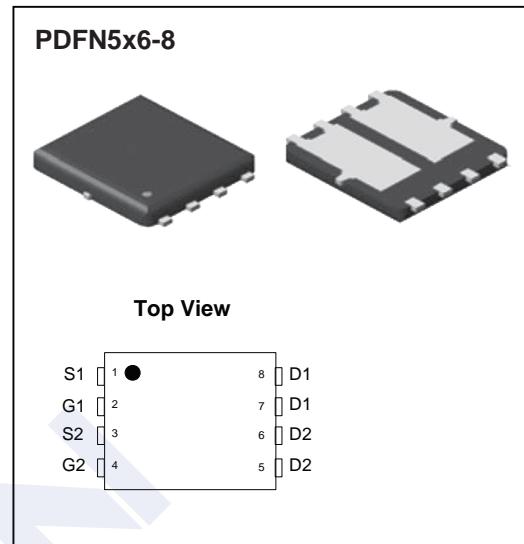
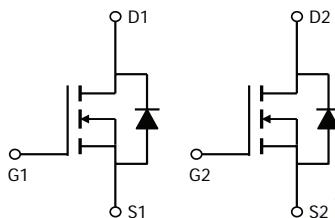


Dual N-Channel MOSFET

2KK6005DFN

■ Features

- V_{DS} (V) = 60 V
- $I_{D\text{MAX}}$ (at V_{GS} = 10 V) = 7.8 A
- $R_{DS(\text{ON})}$ (at V_{GS} = 10 V) = 22.5 mΩ (Typ.)

■ Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±20	V
V_{DS}	Drain-source voltage	60	V
$I_D^{(1)}$	Drain current (continuous) at T_c = 25 °C	20	A
I_D	Drain current (continuous) at T_c = 100 °C	20	A
$I_D^{(2)}$	Drain current (continuous) at T_{pcb} = 25 °C	7.8	A
	Drain current (continuous) at T_{pcb} = 100 °C	5.5	A
$I_{D\text{M}}^{(2)(3)}$	Drain current (pulsed)	31.2	A
P_{TOT}	Total dissipation at T_c = 25 °C	65	W
$P_{\text{TOT}}^{(2)}$	Total dissipation at T_{pcb} = 25 °C	4.3	W
I_{AV}	Non-repetitive avalanche current	7.8	A
$E_{AS}^{(4)}$	Single pulse avalanche energy	190	mJ
$R_{\text{thj-case}}$	Thermal resistance junction-case	2.3	°C/W
$R_{\text{thj-pcb}}^{(1)}$	Thermal resistance junction-pcb	35	°C/W
T_j	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		°C

Notes:

(1) Current is limited by bonding, with $R_{\text{thJC}} = 2.3 \text{ °C/W}$; the chip is able to carry 30 A at 25 °C.

(2) When mounted on an 1 inch² 2 Oz. Cu board, $t < 10$ s

(3) Pulse width is limited by safe operating area.

(4) Starting T_j = 25 °C, I_D = I_{AS} , V_{DD} = 25 V

(5) When mounted on an 1 inch² 2 Oz. Cu board, $t < 10$ s

Dual N-Channel MOSFET

2KK6005DFN

■ Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 60 \text{ V}$			1	μA
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
$V_{\text{GS}(\text{th})}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	1		2.5	V
$R_{\text{DS}(\text{on})}$	Static drain-source on-resistance	$V_{\text{GS}} = 10 \text{ V}, I_D = 4 \text{ A}$		22.5	30	$\text{m}\Omega$
		$V_{\text{GS}} = 5 \text{ V}, I_D = 4 \text{ A}$		30	44	$\text{m}\Omega$
C_{iss}	Input capacitance	$V_{\text{DS}} = 25 \text{ V}, f = 1 \text{ MHz}, V_{\text{GS}} = 0 \text{ V}$	-	668	-	pF
C_{oss}	Output capacitance		-	144	-	pF
C_{rss}	Reverse transfer capacitance		-	14	-	pF
Q_g	Total gate charge	$V_{\text{DD}} = 30 \text{ V}, I_D = 7.8 \text{ A}, V_{\text{GS}} = 0 \text{ to } 10 \text{ V}$	-	13	-	nC
Q_{gs}	Gate-source charge		-	2.4	-	nC
Q_{gd}	Gate-drain charge		-	3	-	nC
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}$ open drain	-	4	-	Ω
$t_{\text{d}(\text{on})}$	Turn-on delay time	$V_{\text{DD}} = 30 \text{ V}, I_D = 4 \text{ A}, R_G = 4.7 \Omega, V_{\text{GS}} = 10 \text{ V}$	-	9	-	ns
t_r	Rise time		-	7.7	-	ns
$t_{\text{d}(\text{off})}$	Turn-off delay time		-	32.5	-	ns
t_f	Fall time		-	5	-	ns
I_{SD}	Source-drain current		-		7.8	A
$I_{\text{SDM}}^{(1)}$	Source-drain current (pulsed)		-		31.2	A
$V_{\text{SD}}^{(2)}$	Forward on voltage	$V_{\text{GS}} = 0 \text{ V}, I_{\text{SD}} = 7.8 \text{ A}$	-		1.3	V
t_{rr}	Reverse recovery time	$I_{\text{SD}} = 7.8 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}, V_{\text{DD}} = 48 \text{ V}, T_J = 150^\circ\text{C}$	-	30		ns
Q_{rr}	Reverse recovery charge		-	35		nC
I_{RRM}	Reverse recovery current		-	2.35		A

Notes:

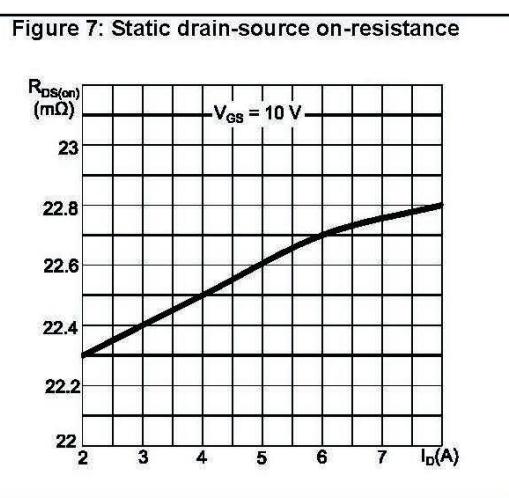
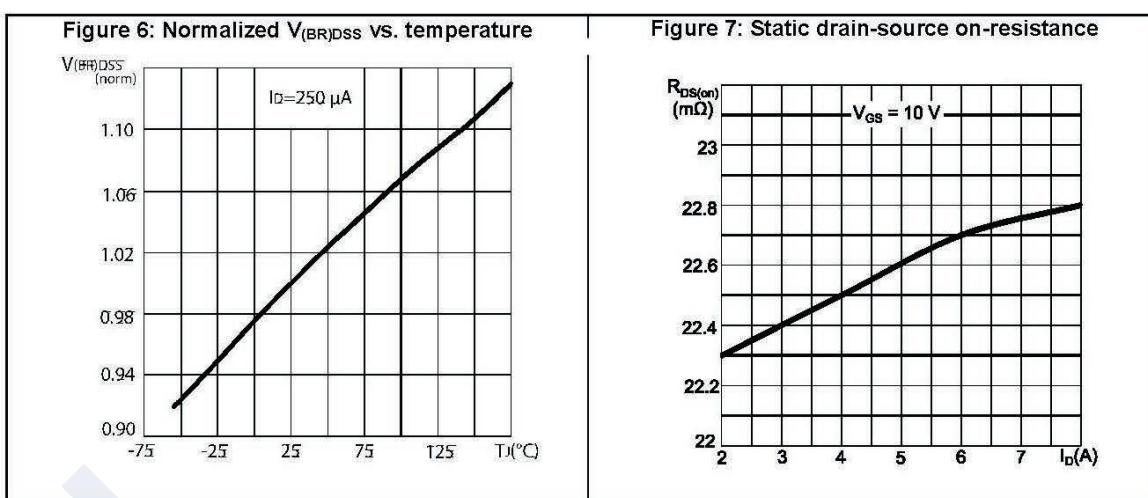
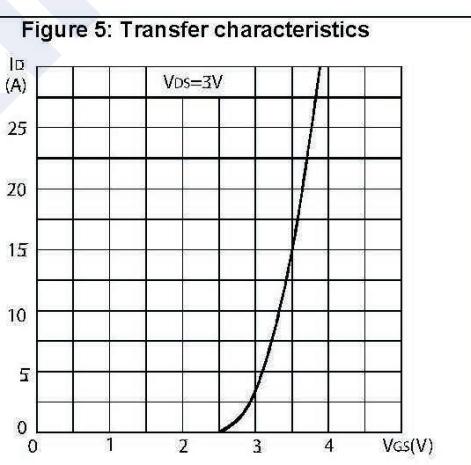
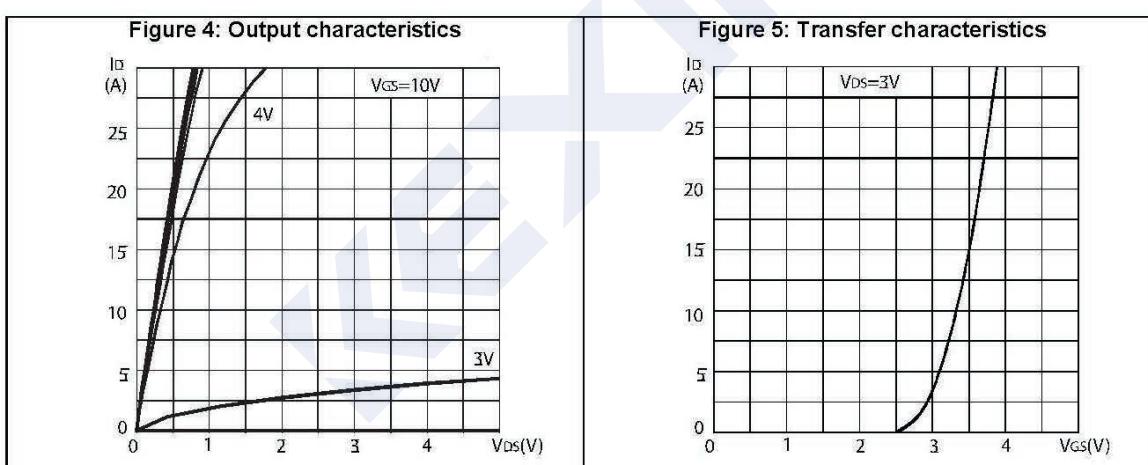
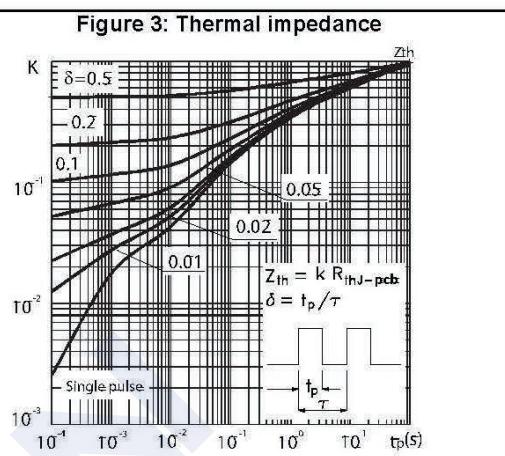
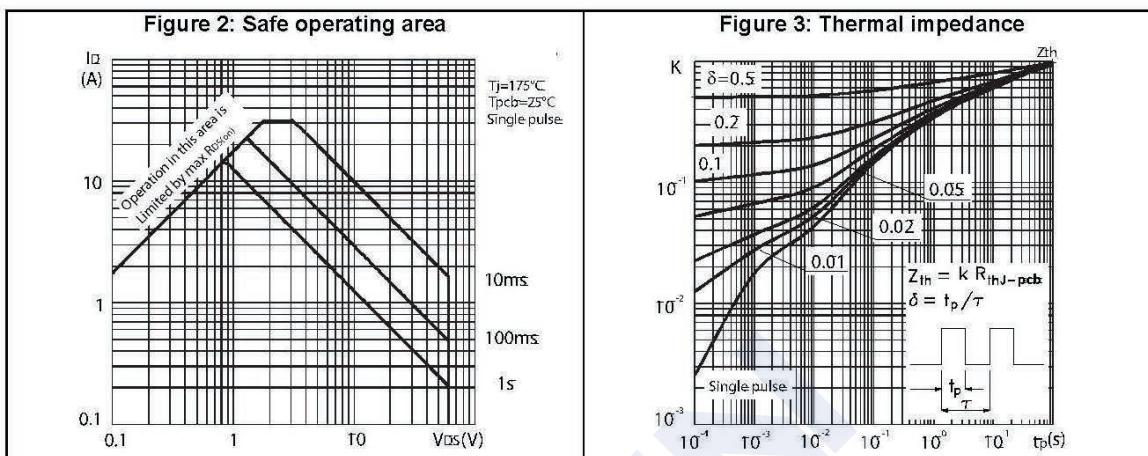
(¹)Pulse width is limited by safe operating area.

(²)Pulse test: pulse duration = 300 μs , duty cycle 1.5%

Dual N-Channel MOSFET

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■ Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified



Dual N-Channel MOSFET

2KK6005DFN

Figure 8: Gate charge vs. gate-source voltage

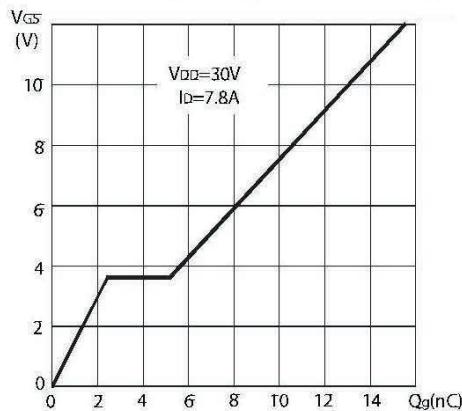


Figure 9: Capacitance variations

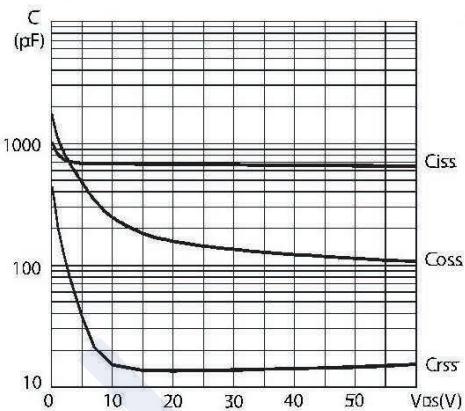


Figure 10: Normalized gate threshold voltage vs. temperature

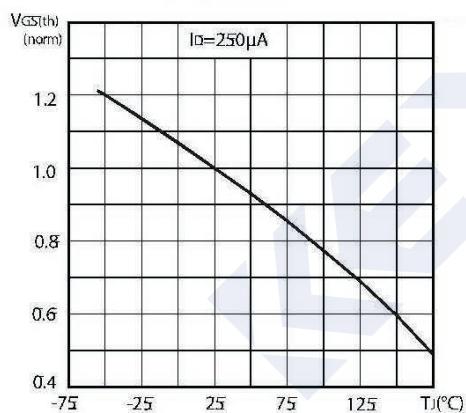


Figure 11: Normalized on-resistance vs. temperature

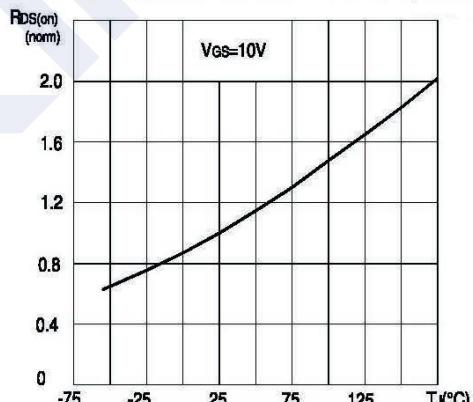
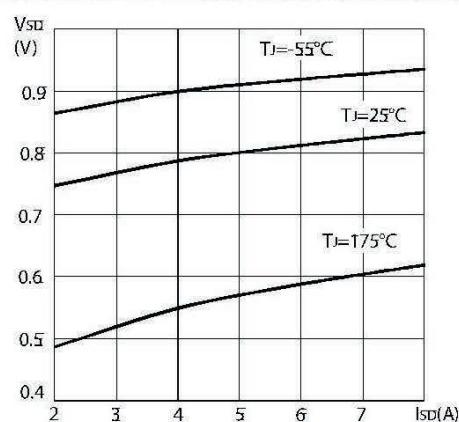


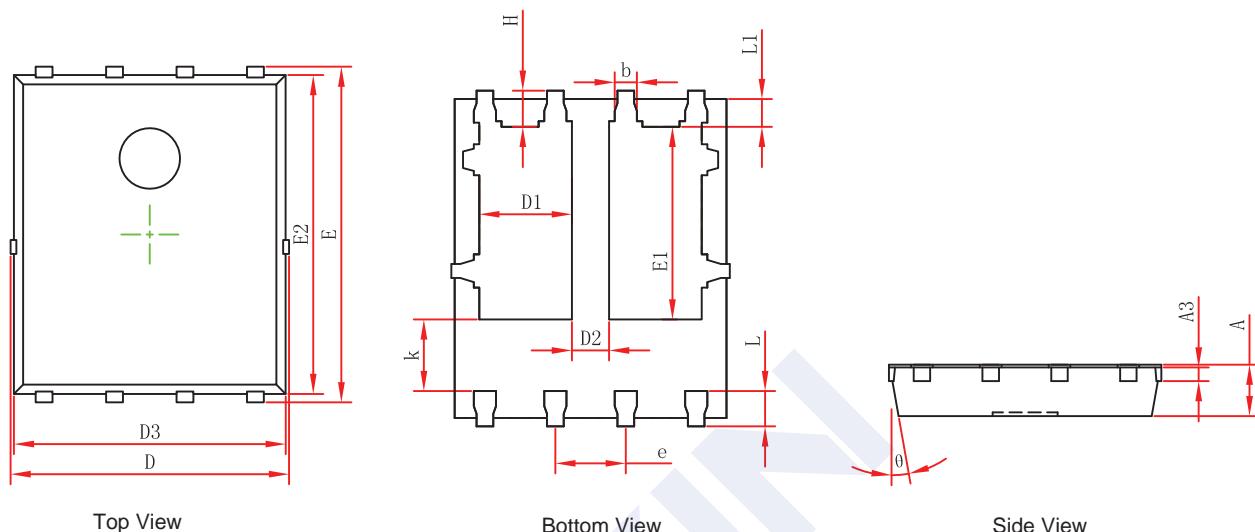
Figure 12: Source-drain diode forward characteristics



Dual N-Channel MOSFET

2KK6005DFN

■ PDFN5x6-8 Package Outline Dimensions



Top View

Bottom View

Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254 REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°